MARKING



TinyLogic HST Inverter NC7ST04

Description

The NC7ST04 is a single high performance CMOS Inverter, with TTL-compatible inputs. Advanced Silicon Gate CMOS fabrication assures high speed and low power circuit operation. ESD protection diodes inherently guard both input and output with respect to the $V_{\rm CC}$ and GND rails. High gain circuitry offers high noise immunity and reduced sensitivity to input edge rate. The TTL-compatible input facilitates TTL to NMOS/CMOS interfacing. Device performance is similar to MM74HCT but with $^{1}/_{2}$ the output current drive of HC/HCT.

Features

- Space Saving SOT23-5, SC-74A and SC-88A 5-Lead Packages
- High Speed; t_{PD} < 7 ns typ, V_{CC} = 5 V, C_L = 15 pF
- Low Quiescent Power; $I_{CC} < 1 \mu A \text{ typ}$, $V_{CC} = 5.5 \text{ V}$
- Balanced Output Drive; 2 mA I_{OL}, -2 mA I_{OH}
- TTL-compatible Inputs
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

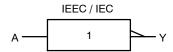


Figure 1. Logic Symbol

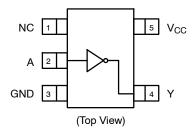
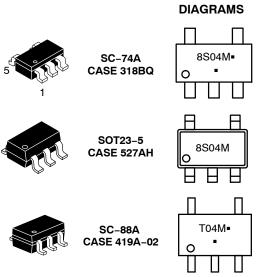


Figure 2. Connection Diagram



8S04, T04 = Specific Device Code M = Date Code*

*Date Code orientation and/or position may vary depending upon manufacturing location.

PIN ASSIGNMENT

Pin Name	Description
Α	Input
Υ	Output
NC	No Connect

FUNCTION TABLE $(Y = \overline{A})$

Input	Output
Α	Υ
L	Н
Н	L

H = HIGH Logic Level L = LOW Logic Level

1

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 3 of this data sheet.

NC7ST04

ABSOLUTE MAXIMUM RATINGS

Symbol	Paramete	Parameter			Unit
V _{CC}	Supply Voltage		-0.5	6.5	V
I _{IK}	DC Input Diode Current	V _{IN} < 0 V	-	-20	mA
		V _{IN} > V _{CC}	-	+20	
V _{IN}	DC Input Voltage	-	-0.5	V _{CC} + 0.5 V	V
lok	DC Output Diode Current	V _{OUT} < 0 V	-	-20	mA
		V _{OUT} > V _{CC}	-	+20	
V _{OUT}	DC Output Voltage		-0.5	V _{CC} + 0.5 V	V
I _{OUT}	DC Output Source or Sink Current		-	±12.5	mA
I _{CC} or I _{GND}	DC V _{CC} or Ground Current per Supply Pin		-	±25	mA
T _{STG}	Storage Temperature Range		-65	+150	°C
T_J	Junction Temperature		-	150	°C
	DC V _{CC} or Ground Current per (Soldering, 10 Seconds)		-	+260	°C
P_{D}	Power Dissipation in Still Air	SC-74A / SOT23-5	-	390	mW
		SC-88A	-	332	7

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	Supply Voltage		4.5	5.5	V
V _{IN}	Input Voltage		0	V _{CC}	V
V _{OUT}	Output Voltage		0	V _{CC}	V
T _A	Operating Temperature		-40	+85	°C
t _r , t _f	Input Rise and Fall Times	V _{CC} = 5.0 V	0	10	ns/V
θ_{JA}	Thermal Resistance	SC-74A / SOT23-5	-	320	°C/W
		SC-88A	-	377	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTICAL CHARACTERISTICS

				T,	_A = +25°	С	T _A = -40	to +85°C	
Symbol	Parameter	V _{CC} (V)	Conditions	Min	Тур	Max	Min	Max	Unit
V _{IH}	HIGH Level Input Voltage	4.5 – 5.5		2.0	-	_	2.0	-	V
V _{IL}	LOW Level Input Voltage	4.5 – 5.5		-	-	0.8	-	0.8	V
V _{OH}	HIGH Level Output Voltage	4.5	$I_{OH} = -20 \mu\text{A},$	4.4	4.5	_	4.4	_	V
	voltage	4.5	$V_{IN} = V_{IH} \text{ or } V_{IL},$ $I_{OH} = -2 \text{ mA}$	4.18	4.35	-	4.13	_	
V _{OL}	LOW Level Output Voltage	4.5	I _{OL} = 20 μA,	-	0	0.1	-	0.1	V
	vollage	4.5	$V_{IN} = V_{IH}$ or V_{IL} , $I_{OL} = 2$ mA	_	0.10	0.26	-	0.33	
I _{IN}	Input Leakage Current	5.5	$0 \le V_{IN} \le 5.5 \text{ V}$	-	-	±0.1	-	±1.0	μΑ
I _{CC}	Quiescent Supply Current	5.5	V _{IN} = V _{CC} or GND	_	-	1.0	-	10.0	μΑ
I _{CCT}	I _{CC} per Input	5.5	Input V _{IN} = 0.5 V or 2.4 V	_	-	2.0	-	2.9	mA

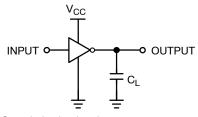
^{1.} Unused inputs must be held HIGH or LOW. They may not float.

AC ELECTRICAL CHARACTERISTICS

					T _A = 25°C		T _A = -40	to 85°C	
Symbol	Parameter	V _{CC} (V)	Conditions	Min	Тур	Max	Min	Max	Unit
t _{PLH} , t _{PHL}	Propagation Delay	5.0	C _L = 15 pF	-	3.5	12	-	_	ns
	(Figure 3, 5)			-	6.0	17	-	_	
		4.5	C _L = 50 pF	-	6.2	16	-	20	
				-	11.4	27	-	31	
		5.5		-	4.3	14	-	18	
				-	11.1	26	-	30	
t _{TLH} , t _{THL}	Output Transition Time	5.0	C _L = 15 pF	-	4	10	-	_	ns
	(Figure 3, 5)	4.5	C _L = 50 pF	-	11	25	-	31	
		5.5		-	10	21	-	26	
C _{IN}	Input Capacitance	Open		-	2	10	-	_	pF
C _{PD}	Power Dissipation Capacitance (Figure 4)	5.00	(Note 2)	_	6	_	_	-	pF

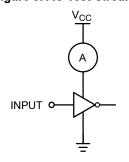
C_{PD} is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I_{CCD}) at no output lading and operating at 50% duty cycle. C_{PD} is related to I_{CCD} dynamic operating current by the expression:
 I_{CCD} = (C_{PD}) (V_{CC}) (f_{IN}) + (I_{CCstatic}).

AC Loading and Waveforms



 C_L includes load and stray capacitance; inputs PRR = 1.0 MHz, t_W = 500 ns.

Figure 3. AC Test Circuit



Input = AC Waveform; PRR = Variable; Duty Cycle = 50%. **Figure 4.** I_{CCD} **Test Circuit**

OUTPUT

1.3 V

1.3 V

1.3 V

1.0%

GND

1.3 V

Figure 5. AC Waveforms

DEVICE ORDERING INFORMATION

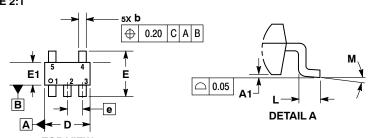
Device	Top Mark	Packages	Shipping [†]
NC7ST04M5X	8S04	SC-74A	3000 / Tape & Reel
NC7ST04M5X-L22090	8S04	SOT23-5	3000 / Tape & Reel
NC7ST04P5X	T04	SC-88A	3000 / Tape & Reel
NC7ST04P5X-L22057	T04	SC-88A	3000 / Tape & Reel

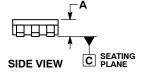
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

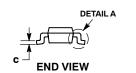


CASE 318BQ ISSUE B

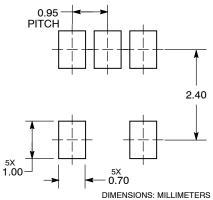
DATE 18 JAN 2018







RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME
 Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH
 THICKNESS. MINIMUM LEAD THICKNESS IS THE
 MINIMUM THICKNESS OF BASE MATERIAL.
 DIMENSIONS A AND R DO NOT INCLUDE MOLD.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.

	MILLIMETERS			
DIM	MIN	MAX		
Α	0.90	1.10		
A1	0.01	0.10		
b	0.25	0.50		
С	0.10	0.26		
D	2.85	3.15		
E	2.50	3.00		
E1	1.35	1.65		
е	0.95 BSC			
L	0.20	0.60		
M	0 °	10°		

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

Μ = Date Code = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	SC-74A		PAGE 1 OF 1

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SC-88A (SC-70-5/SOT-353) CASE 419A-02 ISSUE M

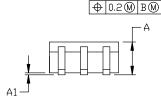
DATE 11 APR 2023

NOTES:

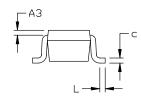
- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. 419A-01 DBSOLETE, NEW STANDARD 419A-02
- 4. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH,
 PROTRUSIONS, OR GATE BURRS.MOLD FLASH, PROTRUSIONS,
 OR GATE BURRS SHALL NOT EXCEED 0.1016MM PER SIDE.

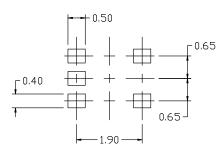
	MILLIMETERS				
DIM	INITETINE LEKS				
	MIN.	N□M.	MAX.		
А	0.80	0.95	1.10		
A1			0.10		
A3	0.20 REF				
b	0.10	0.20	0.30		
С	0.10		0.25		
D	1.80	2.00	2,20		
Е	2.00	2.10	2,20		
E1	1.15	1.25	1.35		
е		0.65 BSI			
L	0.10	0.15	0.30		

E + E1



5X b





RECOMMENDED MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SDLDERRM/D.

GENERIC MARKING DIAGRAM*



*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

XXX = Specific Device Code

M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

STYLE 1:
PIN 1. BASE
EMITTER
3. BASE
COLLECTOR
COLLECTOR

YLE 2	2:
IN 1.	ANODE
2.	EMITTER
3.	BASE
4.	COLLECTOR
5.	CATHODE

STYLE 3: PIN 1. ANODE 1 2. N/C 3. ANODE 2 4. CATHODE 2 5. CATHODE 1 STYLE 4:
PIN 1. SOURCE 1
2. DRAIN 1/2
3. SOURCE 1
4. GATE 1
5. GATE 2

STYLE 5:
PIN 1. CATHODE
2. COMMON ANODE
3. CATHODE 2
4. CATHODE 3
5. CATHODE 4

STYLE 6: PIN 1. EMITTER 2 2. BASE 2 3. EMITTER 1 4. COLLECTOR STYLE 7:
PIN 1. BASE
2. EMITTER
3. BASE
4. COLLECTOR
5. COLLECTOR

STYLE 8: PIN 1. CATHODE 2. COLLECTOR 3. N/C 4. BASE

5. EMITTER

STYLE 9: PIN 1. ANODE 2. CATHODE 3. ANODE 4. ANODE 5. ANODE Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

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DESCRIPTION:

5. COLLECTOR 2/BASE 1

SC-88A (SC-70-5/SOT-353)

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REFERENCE

SOT-23, 5 Lead CASE 527AH **ISSUE A**

DATE 09 JUN 2021

NUTES

A

F1 F

В

DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 19894

DIM

Α

A1

Α2

b

- CONTROLLING DIMENSION: MILLIMETERS
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE
- DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS, MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.25 PER SIDE. D AND E1 DIMENSIONS ARE DETERMINED AT DATUM D.

MIN.

0.90

0.00

0.90

0.30

DIMENSION 'b' DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL BE O. 08mm TOTAL IN EXCESS OF THE 'b' DIMENSION AT MAXIMUM MATERIAL CONDITION. MINIMUM SPACE BETWEEN PROTRUSION AND AN ADJACENT LEAD SHALL NOT BE LESS THAN 0.07mm.

MILLIMETERS

ИПМ.

1.15

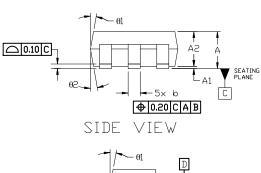
MAX.

1.45

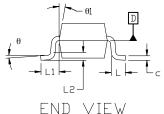
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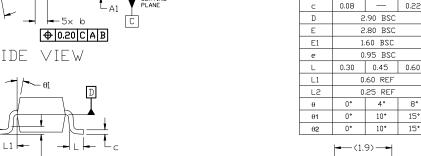
1.30

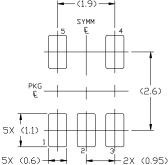
0.50



TOP VIEW







GENERIC MARKING DIAGRAM*



XXX = Specific Device Code = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "=", may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please download the $\square N$ Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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